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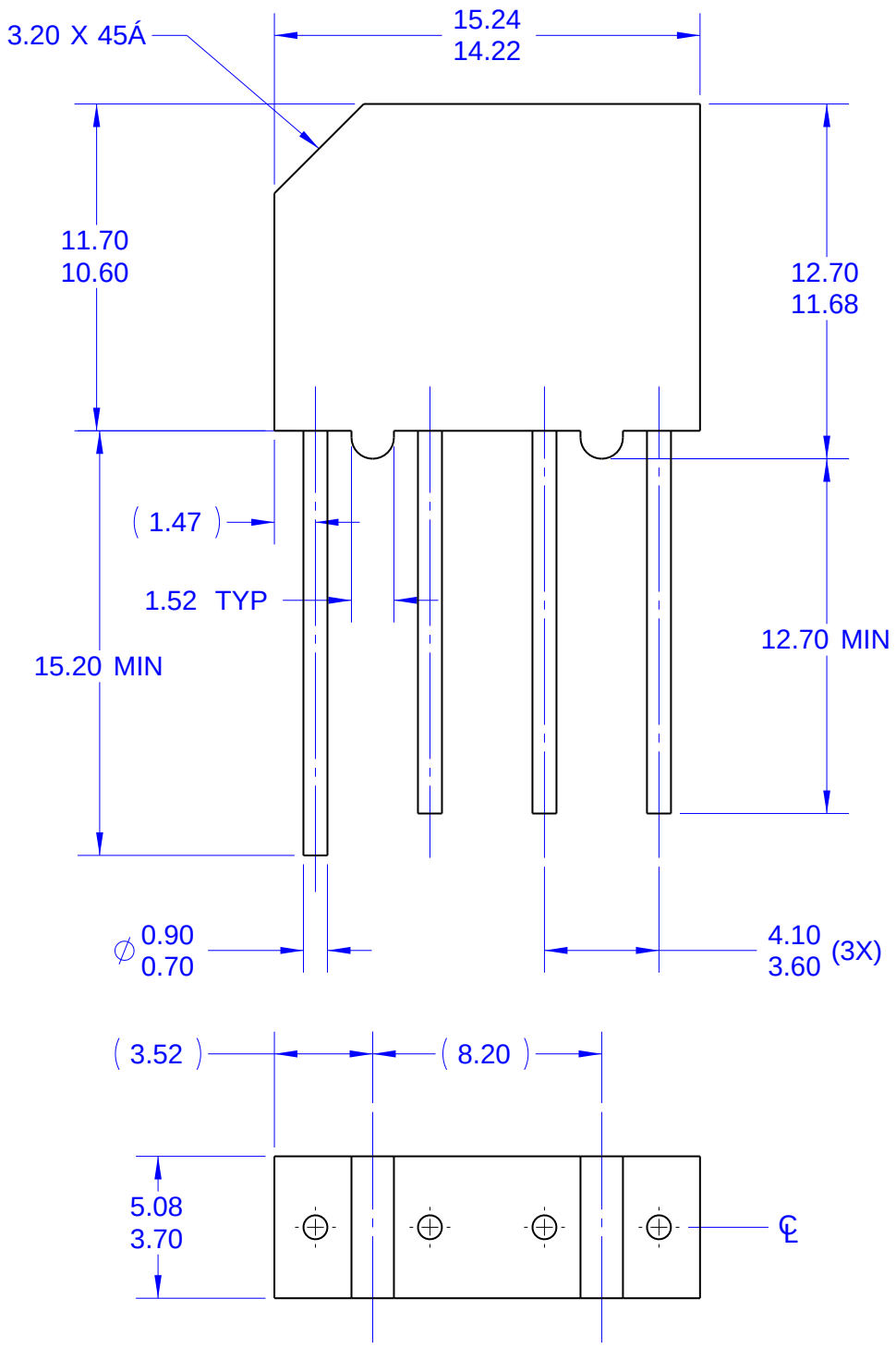
REVISIONS

NBR	DESCRIPTION	DATE	BY/APP'D
1	RELEASED TO DCC	27AUG08	HYANG/ SUZHOU



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A. THIS PACKAGE DOES NOT CONFORMS TO ANY STANDARD.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
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F. DRAWING FILE NAME: KBPM04AREV1

APPROVALS	DATE
DRAWN: BOBOY MALDO	27AUG08
CHECKED: BENJO ROLUNA	
APPROVED: HENRY YANG	
APPROVED: HOWARD ALLEN	

PROJECTION [MM] INCH

FAIRCHILD SEMICONDUCTOR™

4LD, KBPM, THROUGH-HOLE, MOLDED PACKAGE

SCALE	SIZE	DRAWING NUMBER	REV
1:1	N/A	MKT-KBPM04A	1

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SHEET : 1 OF 1